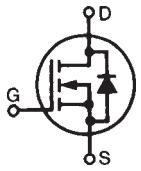
IXYS

Polar™ Power MOSFET HiPerFET™

IXFB44N100P

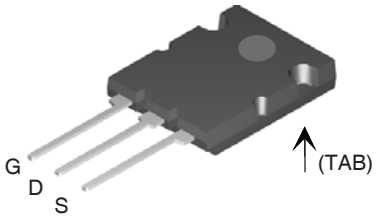
V_{DSS} = 1000V
I_{D25} = 44A
$R_{DS(on)}$ ≤ 220mΩ
t_{rr} ≤ 300ns

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1000	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1000	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	T_C = 25°C	44	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	110	A
I_{AR}	T_C = 25°C	22	A
E_{AS}	T_C = 25°C	2	J
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	15	V/ns
P_D	T_C = 25°C	1250	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10s	260	°C
F_C	Mounting torque	30..120/6.7..27	N/lb.
Weight		10	g

PLUS264™ (IXFB)



G = Gate D = Drain
S = Source TAB = Drain

Features

- Fast recovery diode
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect

Advantages

- Plus 264™ package for clip or spring mounting
- Space savings
- High power density

Applications

- Switched-mode and resonant-mode power supplies
- DC-DC Converters
- Laser Drivers
- AC and DC motor controls
- Robotics and servo controls

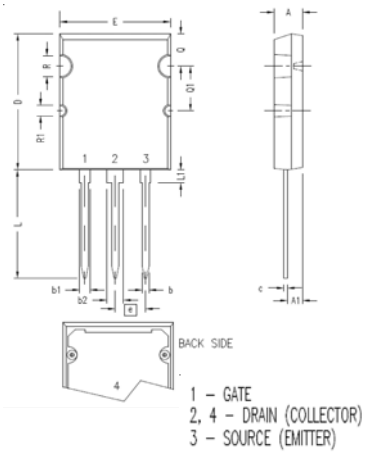
Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 1mA	3.5		6.5	V
I_{GSS}	V_{GS} = ± 30V, V_{DS} = 0V			± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$			50	μA
	V_{GS} = 0V, T_J = 125°C			3	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			220	mΩ

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 0.5 • I_{D25}, Note 1	20	35		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		19		nF
C_{oss}			1060		pF
C_{rss}			41		pF
R_{Gi}	Gate input resistance		1.70		Ω
$t_{d(on)}$	**Resistive Switching Times**		60		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		68		ns
$t_{d(off)}$	R_G = 1Ω (External)		90		ns
t_f			56		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		305		nC
Q_{gs}			104		nC
Q_{gd}			126		nC
R_{thJC}				0.10	°C/W
R_{thCS}			0.13		°C/W

Source-Drain Diode (T_J = 25°C unless otherwise specified)		Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			44	A
I_{SM}	Repetitive, pulse width limited by T_{JM}			176	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 22A, -di/dt = 100A/μs			300	ns
Q_{RM}	V_R = 100V		2.5		μC
I_{RM}			17		A

Note 1: Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

PLUS264™ (IXFB) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215 BSC		5.46 BSC	
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ 25ºC

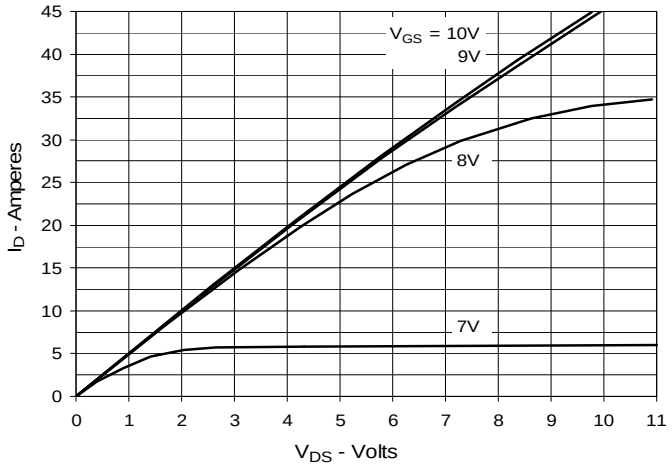


Fig. 2. Extended Output Characteristics @ 25ºC

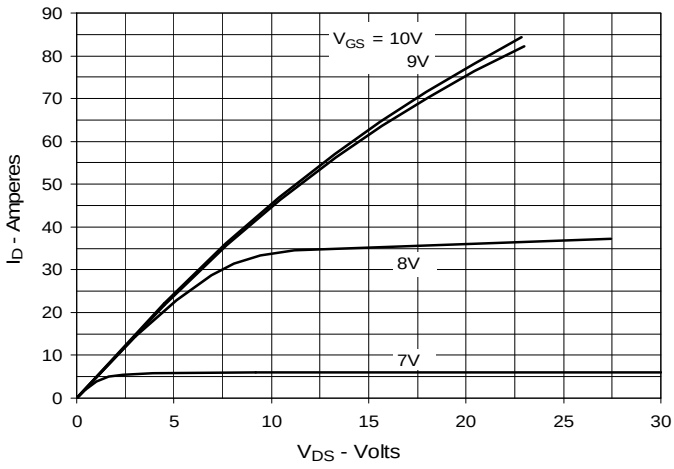


Fig. 3. Output Characteristics @ 125ºC

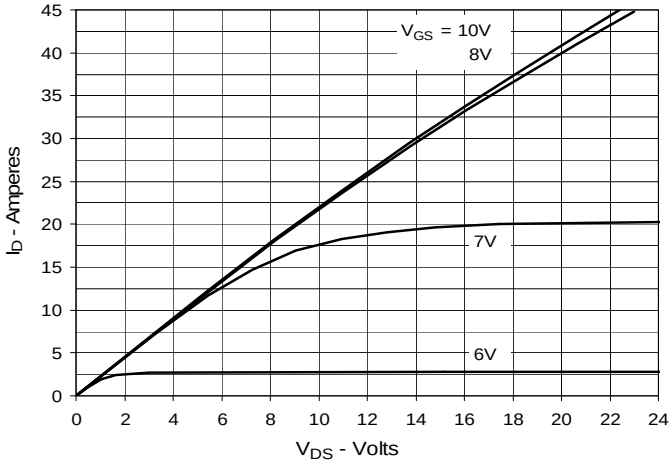


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 22A Value vs. Junction Temperature

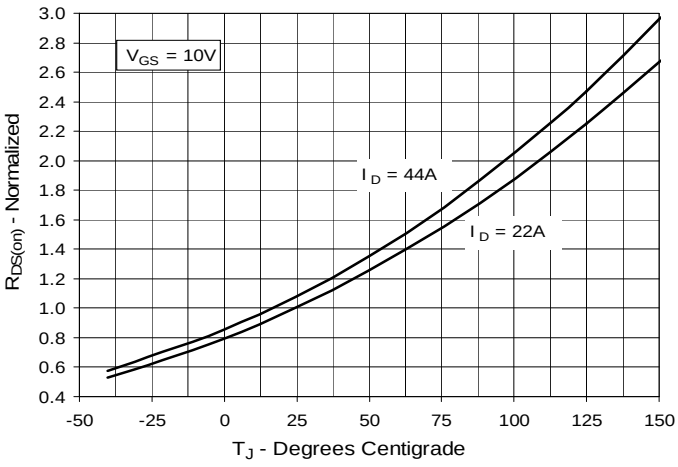


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 22A Value vs. Drain Current

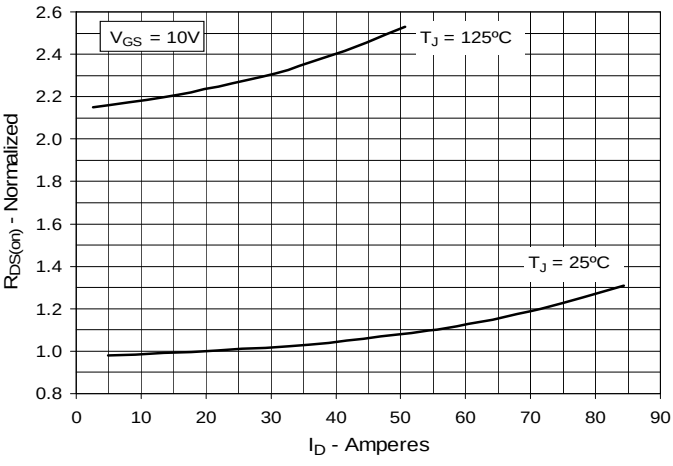


Fig. 6. Maximum Drain Current vs. Case Temperature

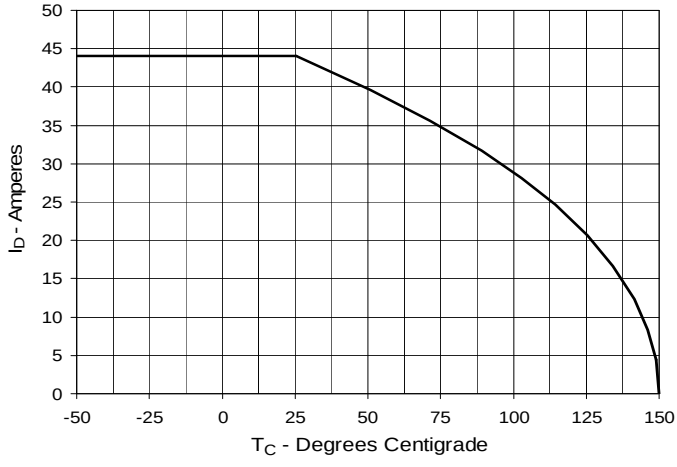


Fig. 7. Input Admittance

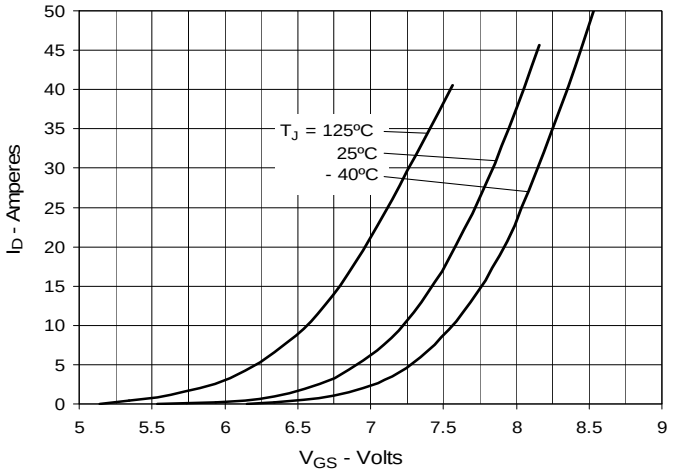


Fig. 8. Transconductance

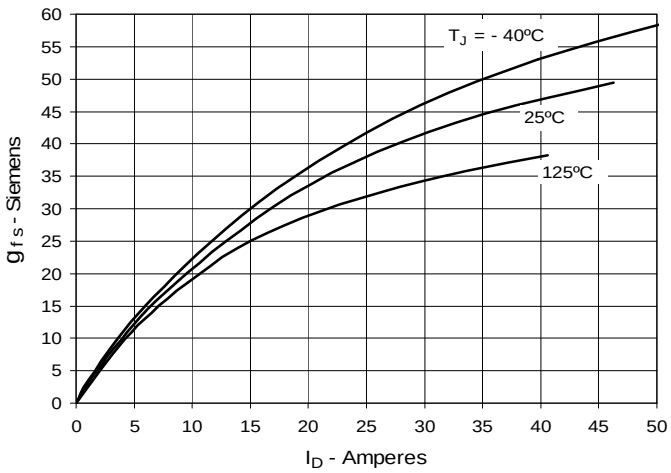


Fig. 9. Forward Voltage Drop of Intrinsic Diode

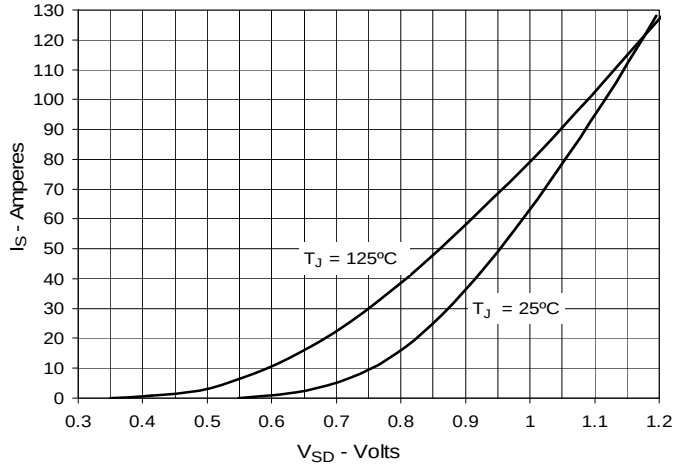


Fig. 10. Gate Charge

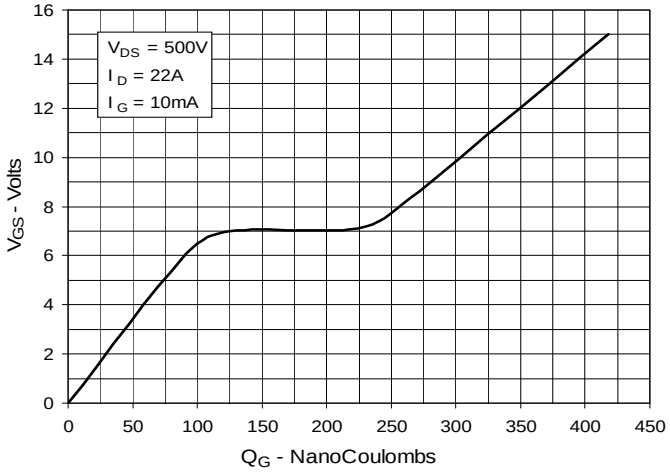


Fig. 11. Capacitance

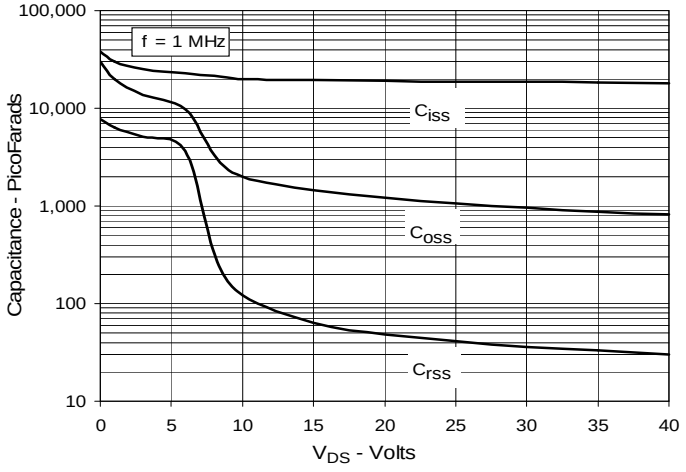


Fig. 12. Maximum Transient Thermal Impedance